

DESIGN CRITERIA CHECKLIST

Critical factors to consider when choosing a potting or encapsulating compound.



Thermal Properties

- Thermal conductivity (W/mk)

- Glass transition (Tg)

- Coefficient of thermal expansion (CTE)

- Hardness and cross-link density

- Operating temperature range



Environmental Conditions

- Elevated temperature

- Thermal cycling

- Thermal shock

- Chemical exposure

- Moisture resistance



Material Properties

- Hardness

- Mechanical properties

- Tensile strength* _____
- Elongation* _____
- Modulus* _____
- Electrical properties

- Dielectric constant* _____
- Dissipation factor* _____
- Volume resistivity* _____
- Dielectric Strength* _____
- Regulatory compliance-chemistry



Process Considerations

- Viscosity/Process temperature

- Pot life/Gel time

- Cure time

- Potting challenges

- Part geometry* _____
- Component configuration* _____
- Mass of application* _____
- Vacuum impregnation vs non-vacuum potting*

- Other considerations* _____
- Dispensing methods

- 1 or 2-component material* _____
- Equipment selection* _____



Material Handling

- Moisture sensitivity

- Homogeneous

- Material prep before use

- Proper container sealing

- Safety considerations

- Proper PPE* _____
- Ventilation* _____
- Understanding chemicals* _____
- Employee training* _____
- Material disposal* _____

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